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SEK 18 male low profile solder and press-in RoHS compliant				Recommended configuration of plated through holes for press-in termination In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties – such as mechanical strength and coefficient of friction – we recommend the following configuration of PCB through holes. <table><tr><td rowspan="3">Tin plated PCB (HAL) acc. to EN 60352-5</td><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>Sn</td><td>max. 15 µm</td></tr><tr><td rowspan="3">Chemical tin plated PCB</td><td>plated hole Ø</td><td>0,94 – 1,09 mm</td></tr><tr><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td rowspan="5">Gold /Nickel plated PCB</td><td>Sn</td><td>min. 0,8µm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr><tr><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>Ni</td><td>3 – 7 µm</td></tr><tr><td rowspan="3">Silver plated PCB</td><td>Au</td><td>0,05 – 0,12 µm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr><tr><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td rowspan="3">Copper plated PCB (OSP)</td><td>Cu</td><td>min. 25 µm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr></table>				Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Sn	max. 15 µm	Chemical tin plated PCB	plated hole Ø	0,94 – 1,09 mm	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Gold /Nickel plated PCB	Sn	min. 0,8µm	plated hole Ø	1,00 – 1,10 mm	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Ni	3 – 7 µm	Silver plated PCB	Au	0,05 – 0,12 µm	plated hole Ø	1,00 – 1,10 mm	Drilled hole Ø	1,15-0,03 mm	Copper plated PCB (OSP)	Cu	min. 25 µm	plated hole Ø	1,00 – 1,10 mm																																																			
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Derating diagram acc to IEC 60512-2 (Current carrying capacity) The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals. The current capacity-curve is valid for continuous, not interrupted current-loaded contacts of connectors when simultaneous power on all contacts is given without exceeding the maximum temperature. Control and test procedures according to DIN IEC 60512. 1) Temperature rise 2) Derating 3) Derating curve at I max x 0.8(IEC 60512-2)				All rights reserved Department EC PD – DE HARTING Electronics GmbH D-32339 Espelkamp Scale 1:1 Free size tol. Created by STORCK Inspected by LEHNERT Standardisation HOFFMANN Date 2016-09-05 State Final Release Title SEK 18 male low profile solder and press-in Doc-Key / ECM-Nr. 100554984/UGD/001/F 500000107692 Type DS Number 09181100001 Rev. F Page 1/1																																																																																											
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